MOSFETs Silicon N-Channel MOS (DTMOSIV)

# TK20V60W5

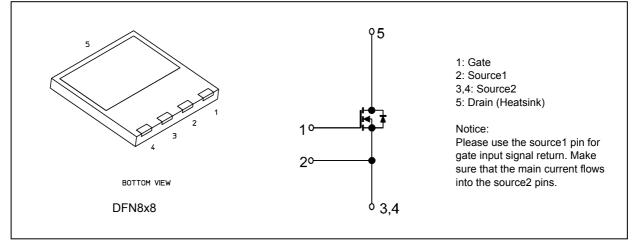
#### 1. Applications

Switching Voltage Regulators

#### 2. Features

- (1) Fast reverse recovery time:  $t_{rr} = 110$  ns (typ.)
- (2) Low drain-source on-resistance:  $R_{DS(ON)} = 0.156 \Omega(typ.)$
- (3) Easy to control Gate switching
- (4) Enhancement mode:  $V_{th}$  = 3 to 4.5 V( $V_{DS}$  = 10 V,  $I_D$  = 1 mA)

#### 3. Packaging and Internal Circuit



#### 4. Absolute Maximum Ratings (Note) ( $T_a = 25 \ ^{\circ}C$ unless otherwise specified)

| Characteristics                |          | Symbol           | Rating     | Unit |
|--------------------------------|----------|------------------|------------|------|
| Drain-source voltage           |          | V <sub>DSS</sub> | 600        | V    |
| Gate-source voltage            |          | V <sub>GSS</sub> | ±30        | 7    |
| Drain current (DC)             | (Note 1) | I <sub>D</sub>   | 20         | Α    |
| Drain current (pulsed)         | (Note 1) | I <sub>DP</sub>  | 80         | 1    |
| Power dissipation              |          | PD               | 156        | W    |
| Single-pulse avalanche energy  | (Note 2) | E <sub>AS</sub>  | 200        | mJ   |
| Avalanche current              |          | I <sub>AR</sub>  | 5          | Α    |
| Reverse drain current (DC)     | (Note 1) | I <sub>DR</sub>  | 20         | 1    |
| Reverse drain current (pulsed) | (Note 1) | I <sub>DRP</sub> | 80         | 1    |
| Channel temperature            |          | T <sub>ch</sub>  | 150        | °C   |
| Storage temperature            |          | T <sub>stg</sub> | -55 to 150 | ]    |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

| Characteristics                    | Symbol                | Max | Unit |
|------------------------------------|-----------------------|-----|------|
| Channel-to-case thermal resistance | R <sub>th(ch-c)</sub> | 0.8 | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: V\_DD = 90 V, T\_ch = 25 °C (initial), L = 14 mH, R\_G = 25  $\Omega$ , I\_AR = 5 A

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

#### 6. Electrical Characteristics

#### 6.1. Static Characteristics (T<sub>a</sub> = 25 °C unless otherwise specified)

| Characteristics                | Symbol               | Test Condition                                | Min | Тур.  | Max  | Unit |
|--------------------------------|----------------------|---|-----|-------|------|------|
| Gate leakage current           | I <sub>GSS</sub>     | $V_{GS}$ = ±30 V, $V_{DS}$ = 0 V              | _   | _     | ±1   | μA   |
| Drain cut-off current          | I <sub>DSS</sub>     | $V_{DS}$ = 600 V, $V_{GS}$ = 0 V              | _   | _     | 100  |      |
| Drain-source breakdown voltage | V <sub>(BR)DSS</sub> | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V | 600 | _     | —    | V    |
| Gate threshold voltage         | V <sub>th</sub>      | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA | 3   | —     | 4.5  |      |
| Drain-source on-resistance     | R <sub>DS(ON)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A |     | 0.156 | 0.19 | Ω    |

#### 6.2. Dynamic Characteristics (Ta = 25 °C unless otherwise specified)

| Characteristics                | Symbol             | Test Condition                                      | Min | Тур. | Max | Unit |
|--------------------------------|--------------------|---|-----|------|-----|------|
| Input capacitance              | C <sub>iss</sub>   | $V_{DS}$ = 300 V, $V_{GS}$ = 0 V, f = 1 MHz         | _   | 1800 | _   | pF   |
| Reverse transfer capacitance   | C <sub>rss</sub>   |   | _   | 5.5  | —   |      |
| Output capacitance             | C <sub>oss</sub>   |   | _   | 45   | _   |      |
| Effective output capacitance   | C <sub>o(er)</sub> | $V_{DS}$ = 0 to 400 V, $V_{GS}$ = 0 V               | _   | 70   | _   |      |
| Gate resistance                | rg                 | V <sub>DS</sub> = OPEN , f = 1 MHz                  | _   | 1.5  | _   | Ω    |
| Switching time (rise time)     | t <sub>r</sub>     | See Figure 6.2.1                                    |     | 45   | _   | ns   |
| Switching time (turn-on time)  | t <sub>on</sub>    |   | _   | 90   | _   |      |
| Switching time (fall time)     | t <sub>f</sub>     | ]   |     | 6    | _   |      |
| Switching time (turn-off time) | t <sub>off</sub>   | ]   |     | 100  |     |      |
| MOSFET dv/dt ruggedness        | dv/dt              | V <sub>DD</sub> = 0 to 400 V, I <sub>D</sub> = 10 A | 50  | _    | _   | V/ns |

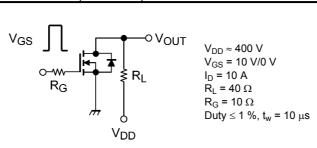


Fig. 6.2.1 Switching Time Test Circuit

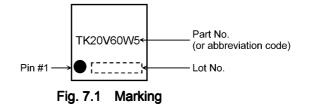
#### 6.3. Gate Charge Characteristics ( $T_a = 25$ °C unless otherwise specified)

| Characteristics                                 | Symbol           | Test Condition   | Min | Тур. | Max | Unit |
|---|------------------|--|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | Qg               | V <sub>DD</sub> = 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A | _   | 55   | —   | nC   |
| Gate-source charge 1                            | Q <sub>gs1</sub> |  | _   | 17   | _   |      |
| Gate-drain charge                               | Q <sub>gd</sub>  |  |     | 33   | _   |      |

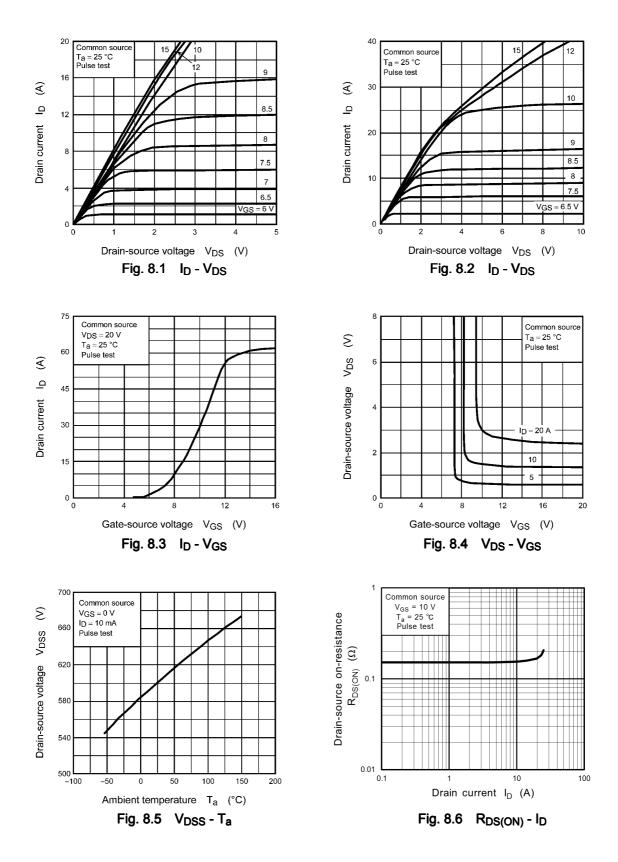
#### 6.4. Source-Drain Characteristics ( $T_a = 25$ °C unless otherwise specified)

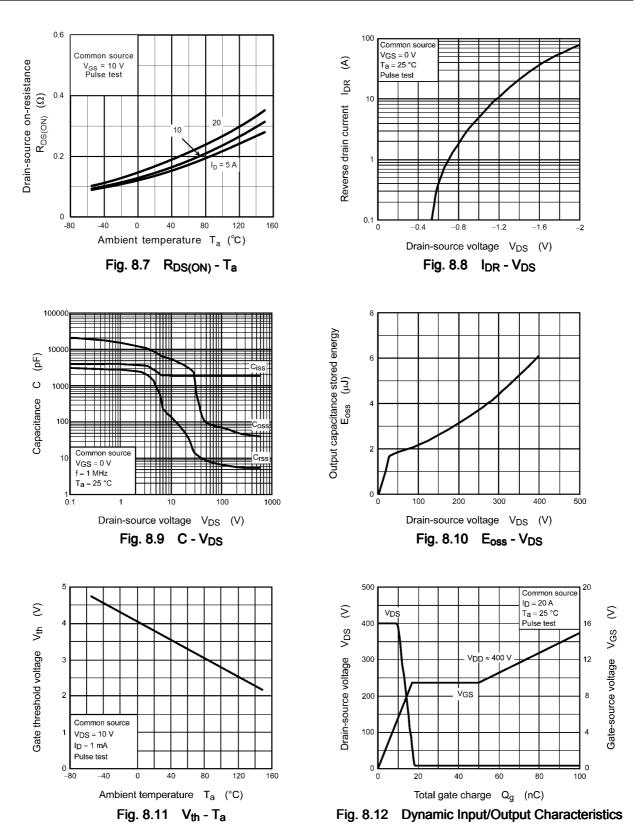
| Characteristics               | Symbol           | Test Condition                                    | Min | Тур. | Max  | Unit |
|-------------------------------|------------------|---|-----|------|------|------|
| Diode forward voltage         | V <sub>DSF</sub> | I <sub>DR</sub> = 20 A, V <sub>GS</sub> = 0 V     | _   |      | -1.7 | V    |
| Reverse recovery time         | t <sub>rr</sub>  | I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V     | _   | 110  | 176  | ns   |
| Reverse recovery charge       | Q <sub>rr</sub>  | -dl <sub>DR</sub> /dt = 100 A/μs                  | _   | 0.6  | _    | μC   |
| Peak reverse recovery current | I <sub>rr</sub>  |   | _   | 10   | _    | А    |
| Diode dv/dt ruggedness        | dv/dt            | $I_{DR}$ = 10 A, $V_{GS}$ = 0 V, $V_{DD}$ = 400 V | 50  |      |      | V/ns |

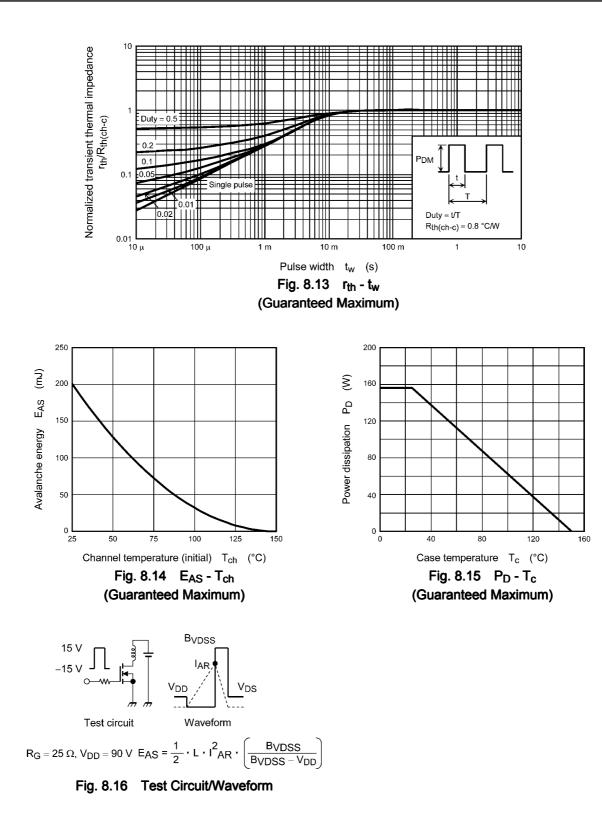
### 7. Marking

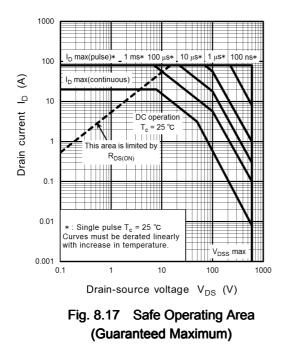


#### 8. Characteristics Curves (Note)





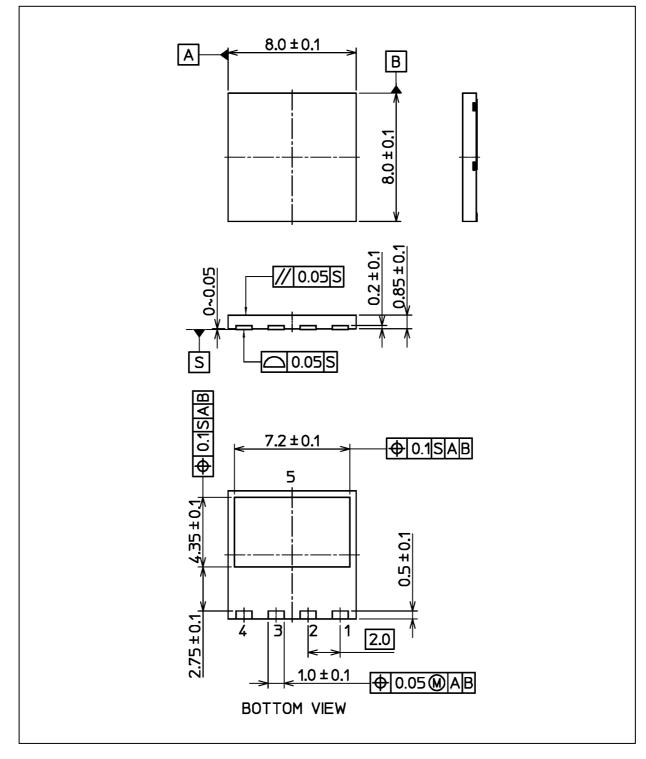




Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

#### Package Dimensions

Unit: mm



#### Weight: 0.175 g (typ.)

Package Name(s)

TOSHIBA: 2-8T1A

Nickname: DFN8x8

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